

BYD17D - BYD17M

GENERAL PURPOSE CONTROLLED AVALANCHE RECTIFIERS

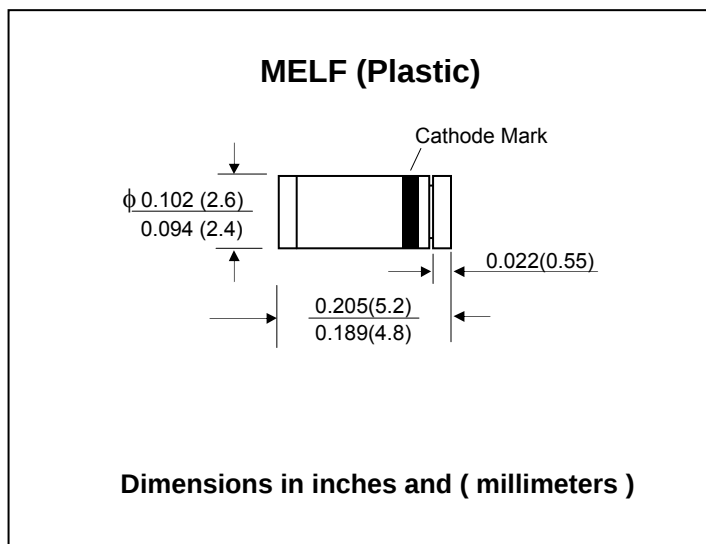
PRV : 200 - 1000 Volts
Io : 1.5 Amperes

FEATURES :

- * Glass passivated
- * High maximum operating temperature
- * Low leakage current
- * Excellent stability
- * Guaranteed avalanche energy absorption capability
- * Smallest surface mount rectifier outline
- * Pb / RoHS Free

MECHANICAL DATA :

- * Case : Molded plastic
- * Terminals : Plated Terminals, solderable per MIL-STD-750 Method 2026
- * Polarity : Color band denotes cathode end
- * Mounting position : Any
- * Weight : 0.116 gram



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (Tj = 25 °C unless otherwise specified.)

RATING	SYMBOL	BYD 17D	BYD 17G	BYD 17J	BYD 17K	BYD 17M	UNIT
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	V
Maximum Crest Working Reverse Voltage	V_{RWM}	200	400	600	800	1000	V
Maximum Continuous Reverse Voltage	V_R	200	400	600	800	1000	V
Min. Reverse Avalanche Breakdown Voltage at $I_R = 0.1$ mA	$V_{(BR)R-min}$	225	450	650	900	1100	V
Maximum Average Forward Current $T_{tp} = 105$ °C (Note 1) $T_a = 65$ °C; PCB mounting	$I_{F(AV)}$	1.5					A
		0.6					
Maximum Non-Repetitive Peak Forward Surge Current (Note 2)	I_{FSM}	20					A
Maximum Forward Voltage at $I_F = 1$ A , $T_j = 25$ °C	V_F	1.05					V
at $I_F = 1$ A , $T_j = T_{jmax}$		0.93					
Maximum Reverse Current at $V_R = V_{RRMmax}$, $T_j = 25$ °C	I_R	1.0					μA
at $V_R = V_{RRMmax}$, $T_j = 165$ °C	$I_{R(H)}$	100					μA
Typical Reverse Recovery Time (Note 3)	T_{rr}	3					μs
Thermal Resistance from Junction to Tie-Point	$R_{th j-tp}$	30					K / W
Thermal Resistance from Junction to Ambient (Note 4)	$R_{th j-a}$	150					K / W
Operating Junction Temperature Range	T_j	- 65 to + 175					°C
Storage Temperature Range	T_{STG}	- 65 to + 175					°C

Notes :

- (1) Averaged over any 20 ms period.
- (2) $t = 10$ ms half sine wave; $T_j = T_{jmax}$ prior to surge; $V_R = V_{RRMmax}$
- (3) Reverse Recovery Test Conditions : $I_F = 0.5$ A, $I_R = 1.0$ A, $I_{rr} = 0.25$ A.
- (4) Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper ≥ 40 μm

RATING AND CHARACTERISTIC CURVES (BYD17D - BYD17M)

FIG.1 - MAXIMUM PERMISSIBLE AVERAGE FORWARD CURRENT AS A FUNCTION OF TIE-POINT TEMPERATURE

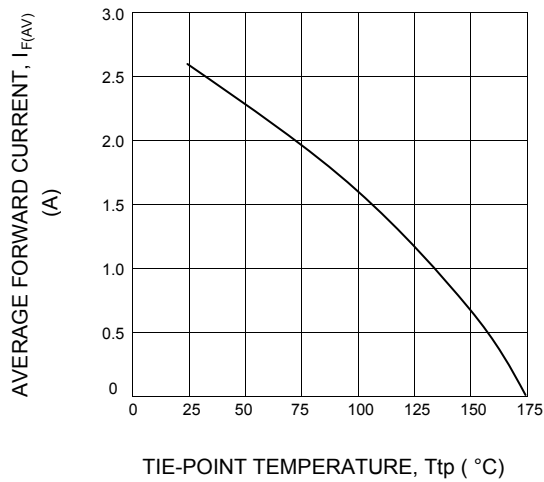


FIG.2 - MAXIMUM PERMISSIBLE AVERAGE FORWARD CURRENT AS A FUNCTION OF AMBIENT TEMPERATURE

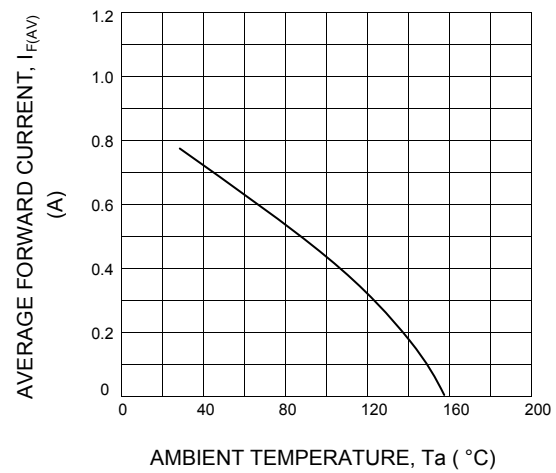


FIG.3 - FORWARD CURRENT AS FUNCTION OF FORWARD VOLTAGE; MAXIMUM VALUES

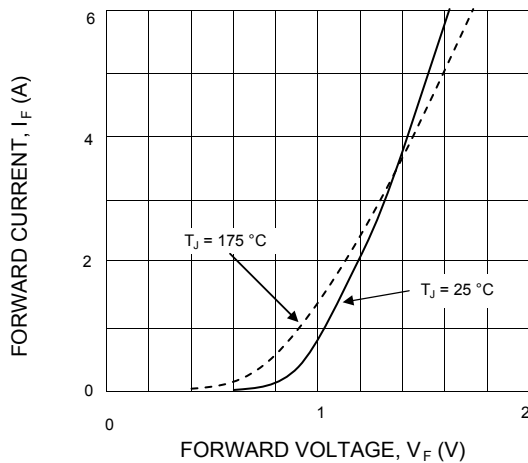


FIG.4 - REVERSE CURRENT AS FUNCTION OF JUNCTION TEMPERATURE; MAXIMUM VALUES

